

# High Speed Infrared Emitting Diode, RoHS-Compliant, 890 nm, Surface Emitter Technology

16758-5

# TSMF1020 TSMF1030 TSMF1030

TSMF1000 series are infrared, 890 nm emitting diodes

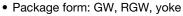
based on surface emitter chip technology with high radiant

power and high speed, molded in clear, untinted plastic

packages (with lens) for surface mounting (SMD).

#### **FEATURES**

Package type: surface-mount





• Peak wavelength: λ<sub>p</sub> = 890 nm

· High radiant power

• Angle of half intensity:  $\varphi = \pm 11^{\circ}$ 

· Low forward voltage

Suitable for high pulse current operation

Package matches with detector TEMD1000

• Floor life: 168 h, MSL 3, according to J-STD-020

 Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912">www.vishav.com/doc?99912</a>

#### **APPLICATIONS**

- IrDA compatible data transmission
- Miniature light barrier
- Photointerrupters
- · Optical switch
- · Control and drive circuits
- Shaft encoders

PRODUCT SUMMARY				
COMPONENT	I <sub>e</sub> (mW/sr)	φ <b>(°)</b>	λ <sub>P</sub> (nm)	t <sub>r</sub> (ns)
TSMF1000	27	± 11	890	15
TSMF1020	27	± 11	890	15
TSMF1030	27	± 11	890	15

#### Note

**DESCRIPTION** 

• Test conditions see table "Basic Characteristics"

ORDERING INFORMATION				
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM	
TSMF1000	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Reverse gullwing	
TSMF1020	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Gullwing	
TSMF1030	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Yoke	

#### Note

· MOQ: minimum order quantity



<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>amb</sub> = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT	
Reverse voltage		V <sub>R</sub>	5	V	
Forward current		I <sub>F</sub>	100	mA	
Peak forward current	$t_p/T = 0.5, t_p = 100 \mu s$	I <sub>FM</sub>	200	mA	
Surge forward current	t <sub>p</sub> = 100 μs	I <sub>FSM</sub>	1	А	
Power dissipation		P <sub>V</sub>	190	mW	
Junction temperature		T <sub>j</sub>	100	°C	
Ambient temperature range		T <sub>amb</sub>	-40 to +85	°C	
Storage temperature range		T <sub>stg</sub>	-40 to +100	°C	
Soldering temperature	t ≤ 5 s	T <sub>sd</sub>	260	°C	
Thermal resistance junction to ambient	JESD51	R <sub>thJA</sub>	250	K/W	

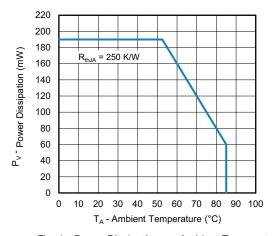


Fig. 1 - Power Dissipation vs. Ambient Temperature

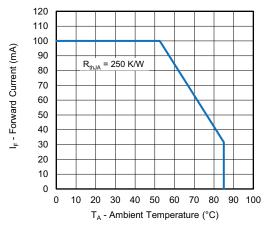


Fig. 2 - Forward Current vs. Ambient Temperature

<b>BASIC CHARACTERISTICS</b> (T <sub>amb</sub> = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I <sub>F</sub> = 20 mA	V <sub>F</sub>	-	1.3	1.5	V
	$I_F = 100 \text{ mA}, t_p = 100 \mu \text{s}$	V <sub>F</sub>	-	1.5	-	V
	$I_F = 1 \text{ A}, t_p = 100 \ \mu\text{s}$	V <sub>F</sub>	-	2.6	-	V
Temperature coefficient of V <sub>F</sub>	I <sub>F</sub> = 20 mA	TK <sub>VF</sub>	-	-1.4	-	mV/K
Reverse current		I <sub>R</sub>	Not designed for reverse operation			μΑ
Junction capacitance	V <sub>R</sub> = 0 V, f = 1 MHz, E = 0	Cj	-	56	-	pF
Podře d State od	I <sub>F</sub> = 20 mA	l <sub>e</sub>	15	27	40	mW/sr
Radiant intensity	$I_F = 100 \text{ mA}, t_p = 100 \mu \text{s}$	l <sub>e</sub>	-	155	-	mW/sr
Radiant power	$I_F = 20 \text{ mA}, t_p = 20 \text{ ms}$	φ <sub>e</sub>	-	10	-	mW
Temperature coefficient of φ <sub>e</sub>	I <sub>F</sub> = 20 mA	TKφ <sub>e</sub>	-	-0.3	-	%/K
Angle of half intensity		φ	-	± 11	-	0
Peak wavelength	I <sub>F</sub> = 20 mA	$\lambda_{p}$	-	890	-	nm
Spectral bandwidth	I <sub>F</sub> = 20 mA	Δλ	-	35	-	nm
Temperature coefficient of $\lambda_p$	I <sub>F</sub> = 20 mA	TKλ <sub>p</sub>	-	0.3	-	nm/K
Rise time	I <sub>F</sub> = 20 mA	t <sub>r</sub>	-	15	-	ns
Fall time	I <sub>F</sub> = 20 mA	t <sub>f</sub>	-	15	-	ns

#### **BASIC CHARACTERISTICS** (T<sub>amb</sub> = 25 °C, unless otherwise specified)

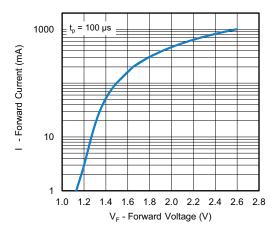


Fig. 3 - Forward Current vs. Forward Voltage

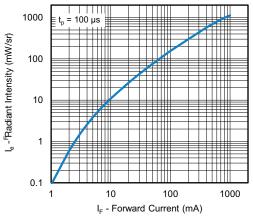


Fig. 4 - Radiant Intensity vs. Forward Current

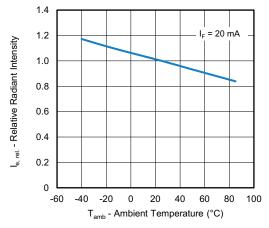


Fig. 5 - Relative Radiant Intensity vs. Ambient Temperature

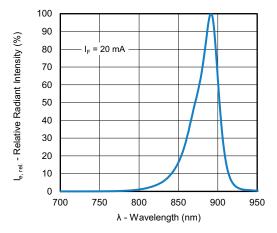


Fig. 6 - Relative Radiant Intensity vs. Wavelength

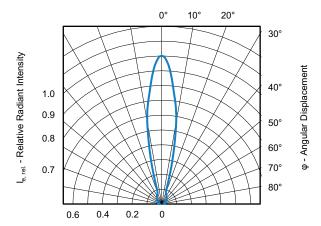


Fig. 7 - Relative Radiant Intensity vs. Angular Displacement

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## Vishay Semiconductors

#### **PRECAUTIONS FOR USE**

#### 1. Over-Current-Proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (burn out will happen).

#### 2. Storage

- Storage temperature and rel. humidity conditions are: 5 °C to 35 °C, R.H. 60 %.
- Floor life must not exceed 168 h, according to JEDEC® level 3, J-STD-020.
  - Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp proof box with desiccant.
  - Considering tape life, we suggest to use products within one year from production date.
- If opened more than one week in an atmosphere 5 °C to 35 °C, R.H. 60 %, devices should be treated at 60 °C  $\pm$  5 °C for 15 h.
- If humidity indicator in the package shows pink color (normal blue), then devices should be treated with the same conditions as 2.3.

#### **REFLOW SOLDER PROFILE**

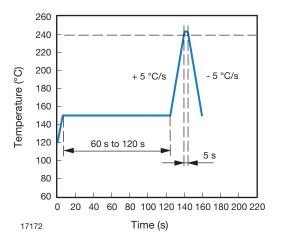


Fig. 8 - Lead Tin (SnPb) Reflow Solder Profile

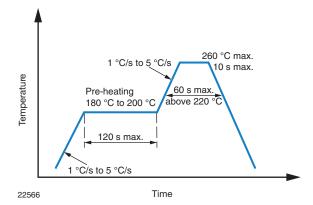
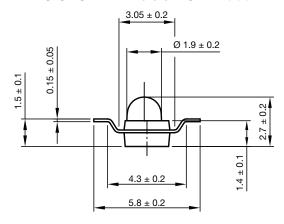


Fig. 9 - Lead (Pb)-Free Reflow Solder Profile According to J-STD-020

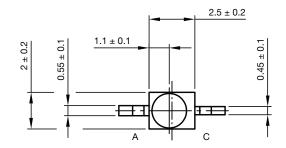


# Vishay Semiconductors

#### **PACKAGE DIMENSIONS** in millimeters: TSMF1000



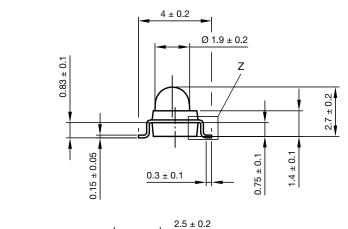




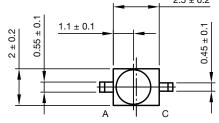
Solder pad proposal

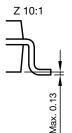
Drawing-No.: 6.544-5326.03-4 Issue: 1; 15.09.2021

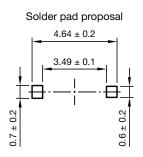
#### **PACKAGE DIMENSIONS** in millimeters: **TSMF1020**







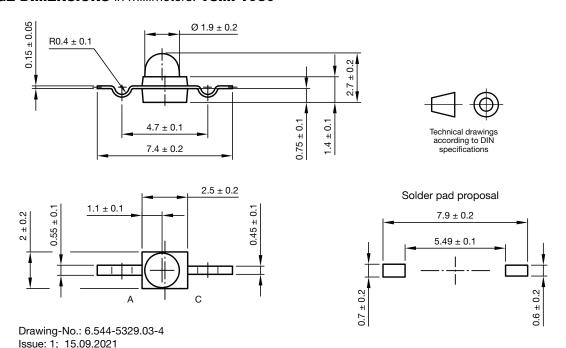




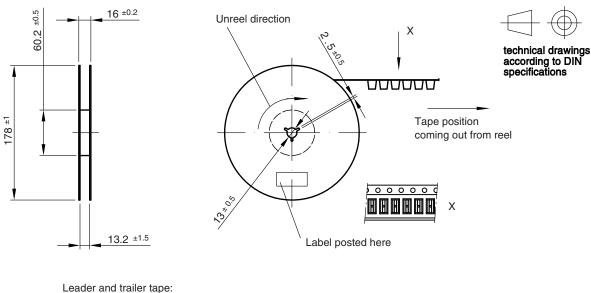
Drawing-No.: 6.544-5325.03-4 Issue: 1; 15.09.2021

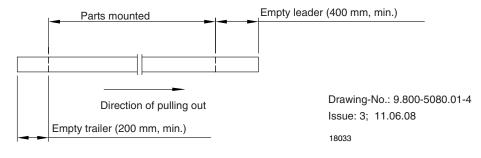


#### **PACKAGE DIMENSIONS** in millimeters: TSMF1030



#### **REEL DIMENSIONS** in millimeters

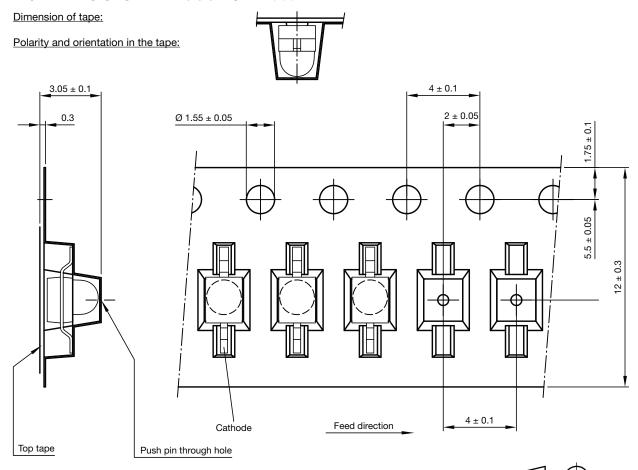








#### **TAPING DIMENSIONS** in millimeters: **TSMF1000**



Quantity per reel: 1000 pieces

Drawing-No.: 9.700-5268.02-4

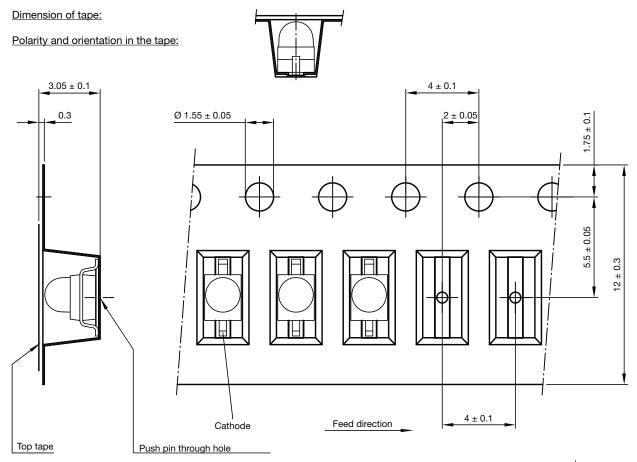
Issue: 1; 28.09.2021





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#### TAPING DIMENSIONS in millimeters: TSMF1020



Quantity per reel: 1000 pieces

Drawing-No.: 9.700-5269.02-4

Issue: 1; 28.09.2021

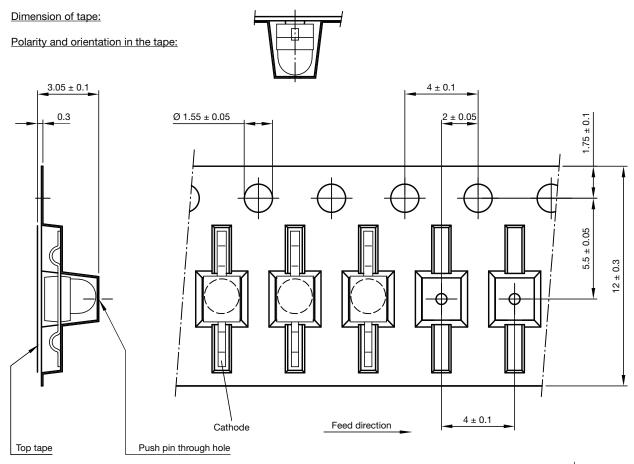


Technical drawings according to DIN specifications



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#### **TAPING DIMENSIONS** in millimeters: **TSMF1030**



Quantity per reel: 1000 pieces

Drawing-No.: 9.700-5270.02-4

Issue: 1; 28.09.2021



Technical drawings according to DIN specifications



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